**Effect of copper surface to HNO$_3$ electrolyte**

Sung-Woo Park, Sang-Jun Han, Young-Kyun Lee, Woo-Sun Lee and Yong-Jin Seo

Department of Electrical Engineering, Chosun University, Department of Electrical Engineering, Daebul University.

**Abstract:** 본 논문에서는 Cu의 ECMP 작용을 위해 HNO$_3$ 전해액의 active, passive, transient, trans-passive 영역을 I-V 특성 곡선을 통해 알아보고, LSV (Linear sweep voltammetry)와 CV (Cyclic voltammetry)법을 통하여 전기화학적 특성을 비교 분석하였다.

**Key Words:** Electrochemical Mechanical Polishing (ECMP), HNO$_3$, Linear sweep voltammetry (LSV), Cyclic voltammetry (CV)